

HSF



ROHS

NOTES

1. MATERIAL:

A. PIN: COPPER Alloy T=0.15MM

B. Housing: Hi-TEMP Plastic UL94V-0, BLACK.

C. Stator: Brass T=0.20MM

2. FINISH: CONTACT: GOLD FLASH (1" MIN.) ALL OVER, 50-100 MICROINCH

(1.27-2.54 MICRON) NICKEL UNDERPLATED ALL OVER

SOLDER TAB: 50-100 (1.27-2.54 MICRON) MICROINCH MATTE TIN,

10-100 MICROINCH (1.27-2.54 MICRON) NICKEL UNDERPLATED

3. ELECTRICAL SPECIFICATIONS:

VOLTAGE RATING: 250 VAC MIN

CURRENT RATING: 2.0 A MIN

DIELECTRIC STRENGTH: 1000 VAC FOR 1 MINUTE MIN

INSULATION RESISTANCE: 1000 MEG OHM MIN

CONTACT RESISTANCE: 50 MILLI OHM MAX

OPERATION TEMPERATURE: -55° C TO +105° C

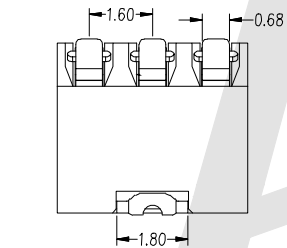
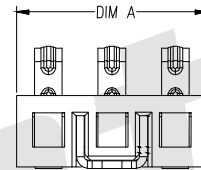
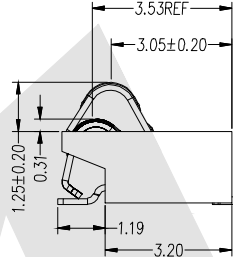
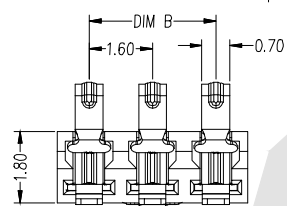
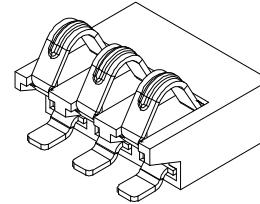
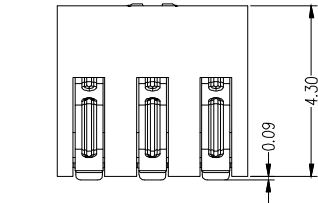
PRODUCT WITHSTANDING REFLOW SOLDERING 260° FOR 10S

4. MECHANICAL SPECIFICATIONS:

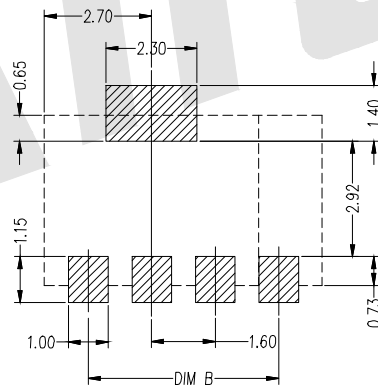
4.1 DURABILITY: 5,000 CYCLES

4.2 MATING FORCE: 2.5kg MAX

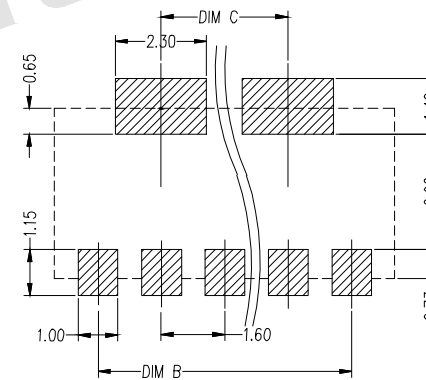
4.3 UNMATING FORCE: 0.5kg MIN



ABT17-10LGXD	16.00	14.40	11.20
ABT17-09LGXD	14.40	12.80	9.60
ABT17-08LGXD	12.80	11.20	8.00
ABT17-07LGXD	11.20	9.60	6.40
ABT17-06LGXD	9.60	8.00	4.80
ABT17-05LGXD	8.00	6.40	3.20
ABT17-04LGXD	6.40	4.80	0
ABT17-03LGXD	4.80	3.20	0
BE FILLED	DIMA	DIMB	DIMC



3&4PIN LAYOUT



5-10PIN LAYOUT

RECOMMENDED PCB LAYOUT

TOL: (<±0.05)

Ordering Code:

ABT17 - X - L - G - X - D

① ② ③ ④ ⑤ ⑥

① Series No: ⑤ Contact Plating:

② No. of Contacts G0: Gold flash

03-10Pin G1: 3u" gold

③ Insulator Material: G2: 5u" gold

P: PBT+30%GF G3: 10u" gold

L: LCP G4: 15u" gold

④ Pitch G5: 30u" gold

G: 1.6mm Pitch ⑥ Packing:

A: Tray

B: Bag

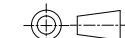
C: Tube

D: Tape Reel

Unless Otherwise specified tolerance

X. ±0.35 X.XX: ±0.20

X.X: ±0.25 X.XXX: ±0.15

SCALE:
As ShownUNIT:
mmDRAW
Wu Feng RongDATE
16/03/2020CHECK
BobYangDATE
16/03/2020

3rd ANGLE PROJECTION



ANTENK ELECTRONICS CO., LTD

Http://www.antenk.com

E-mail: sales@antenk.com

TITLE:

1.6 PITCH 3-10PIN BATTERY CONNECTOR

DRAWING NO:

ABT17-XLGXD

PRODUCT NO:

ABT17-XLGXD



Update Drawing

09/03/2021

DATE

REV

DESCRIPTION